

EAST Search History

Ref #	Hits	Search Query	DBs	Default Operator	Plurals	Time Stamp
L7	10	L4 and tie adj bar near5 (insulat\$3 ceramic dielectric oxide)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2009/06/15 13:17
L6	4	L4 and lead adj frame near5 array	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2009/06/15 13:11
L5	1	L4 and wafer adj level	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2009/06/15 13:11
L4	151	L3 and @ad<="20040225"	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2009/06/15 13:10
L3	167	(257/671).OCLS.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2009/06/15 13:10
L2	3	L1 and lead adj frame with ceramic	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2009/06/15 12:43
L1	42	(US-20020153596-\$ or US- 20050082654-\$ or US- 20020066966-\$ or US- 20020088537-\$ or US- 20020179986-\$ or US- 20050269710-\$ or US- 20010005040-\$ or US- 20030183009-\$ or US- 20020028537-\$ or US- 20020098623-\$ or US- 20030102540-\$).did. or (US- 5915168-\$ or US-5830782-\$ or US-5892417-\$ or US- 5766987-\$ or US-6550664-\$ or US-5969461-\$ or US- 4993000-\$ or US-5286680-\$ or US-5086337-\$ or US- 6096155-\$ or US-6621151-\$ or US-6417574-\$ or US-	US-PGPUB; USPAT	OR	ON	2009/06/15 12:42

		6309910-\$ or US-6081035-\$ or US-5489749-\$ or US-6441481-\$ or US-6417026-\$ or US-4563541-\$ or US-6621163-\$ or US-6710456-\$ or US-6670215-\$ or US-6750083-\$ or US-6753205-\$ or US-6929974-\$ or US-6908791-\$ or US-5139972-\$).did. or (US-6300163-\$ or US-6709894-\$ or US-6911353-\$ or US-5926380-\$ or US-6197616-\$).did.				
S110	8	S108 and acoustic adj wave	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2009/06/15 11:32
S109	18	S108 and (SAW or acoustic adj wave)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2009/06/15 11:32
S108	42	(US-20020153596-\$ or US-20050082654-\$ or US-20020066966-\$ or US-20020088537-\$ or US-20020179986-\$ or US-20050269710-\$ or US-20010005040-\$ or US-20030183009-\$ or US-20020028537-\$ or US-20020098623-\$ or US-20030102540-\$).did. or (US-5915168-\$ or US-5830782-\$ or US-5892417-\$ or US-5766987-\$ or US-6550664-\$ or US-5969461-\$ or US-4993000-\$ or US-5286680-\$ or US-5086337-\$ or US-6096155-\$ or US-6621151-\$ or US-6417574-\$ or US-6309910-\$ or US-6081035-\$ or US-5489749-\$ or US-6441481-\$ or US-6417026-\$ or US-4563541-\$ or US-6621163-\$ or US-6710456-\$ or US-6670215-\$ or US-6750083-\$ or US-6753205-\$ or US-6929974-\$ or US-6908791-\$ or US-5139972-\$).did. or (US-6300163-\$ or US-6709894-\$ or US-6911353-\$ or US-5926380-\$ or US-6197616-\$).did.	US-PGPUB; USPAT	OR	ON	2009/06/15 11:32

S107	62	S106 NOT S104	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2009/06/13 13:40
S106	104	S103 and (lead adj frame) with wafer	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2009/06/13 13:40
S105	19	S104 NOT S100	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2009/06/13 13:39
S104	42	S103 and (lead adj frame) near5 wafer	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2009/06/13 13:39
S103	9336	S102 and (MEMS MEM device semiconductor) with (cap cover lid hermetic seal)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2009/06/13 13:39
S102	53859	S101 and @ad<="20030321"	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2009/06/13 13:39
S101	85473	((257/666-667,678-733,734- 786) or (438/106- 127,461,464)).CCLS.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2009/06/13 13:39
		S104 NOT L9\	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2009/06/13 13:39
S100	23	S94 and (lead adj frame) near5 wafer	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2009/06/13 13:36
S99	548	S97 NOT S98	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2009/06/13 13:26

S98	310	S97 and array	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2009/06/13 13:26
S97	858	S95 NOT S96	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2009/06/13 13:25
S96	44	S95 and wafer adj level	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2009/06/13 13:20
S95	902	S94 and (lead adj frame)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2009/06/13 13:20
S94	2507	S93 and (MEMS MEM device semiconductor) with (cap cover lid hermetic seal)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2009/06/13 13:20
S93	12187	S92 and @ad<="20030321"	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2009/06/13 13:17
S92	19186	((438/110-114,121-126,461,464) or (257/690-697,735-736)).CCLS.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2009/06/13 13:16

6/ 15/ 2009 1:33:20 PM

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